

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of: **Uwe Schwarz**
Serial No: **10/537,211**
I.A. Filing Date: **December 5, 2003**
For: **Production of Microelectromechanical Systems (MEMS)
Using the High-Temperature Silicon Fusion Bonding
of Wafers (as corrected herewith)**

PRELIMINARY AMENDMENT

Introductory Comments

Dear Sir:

Please amend the application as follows.

Amendments to the Specification begin on page 2 of this Amendment.

Amendments to the Claims are reflected in the listing of claims which begins on page 3 of this Amendment. These amended claims shall replace the claims contained in the English translation of the application as submitted herewith.

Remarks begin on page 6 of this Amendment.

